

1. General description

Silicon Carbide Schottky diode in a TO247-2L plastic package, designed for high frequency switched-mode power supplies.



Lead-Free

2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability ($T_{j(max)} = 175\text{ °C}$)

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

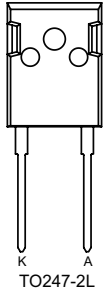
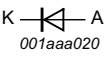
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage			1200			V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 112 °C; Fig. 1 ; Fig. 2 ; Fig. 3		20			A
T _j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 20 A; T _j = 25 °C; Fig. 5		-	1.54	1.75	V
		I _F = 20 A; T _j = 150 °C; Fig. 5		-	2.15	2.60	V
		I _F = 20 A; T _j = 175 °C; Fig. 5		-	2.35	2.80	V
Dynamic characteristics							
Q _r	recovered charge	I _F = 20 A; dI _F /dt = 500 A/μs; V _R = 400 V; T _j = 25 °C; Fig. 7		-	36	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		 001aaa020
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D201200W-B	TO247-2L	WNSC2D201200W-B6Q	Tube	30	TO247L-2L	10-Nov-2020

7. Marking

Table 4. Marking codes

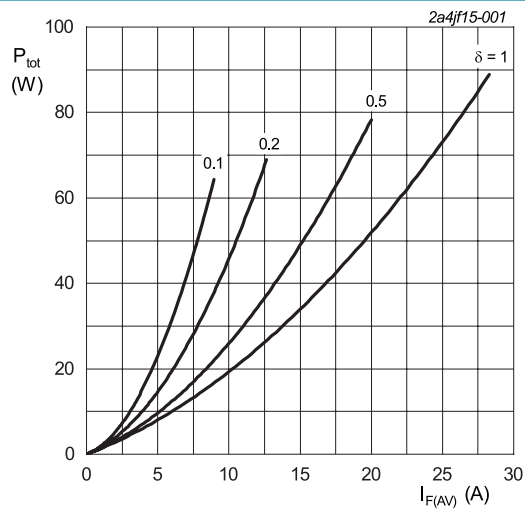
Type number	Marking codes
WNSC2D201200W-B	WNSC2D 201200W-B

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1200	V
V_{RWM}	crest working reverse voltage			1200	V
V_R	reverse voltage	DC		1200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 112\text{ }^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3		20	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 112\text{ }^{\circ}\text{C}$; square-wave pulse		40	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse		140	A
		$t_p = 10\text{ }\mu\text{s}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; square-wave pulse		900	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 10\text{ ms}$		98	A^2s
T_{stg}	storage temperature			-55 to 175	$^{\circ}\text{C}$
T_j	junction temperature			-55 to 175	$^{\circ}\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.268\text{ V}; R_s = 0.0662\text{ }\Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

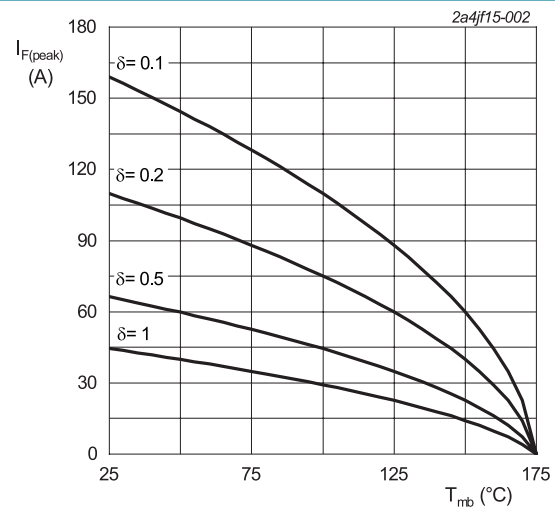


Fig. 2. Current derating as a function of mounting base temperature

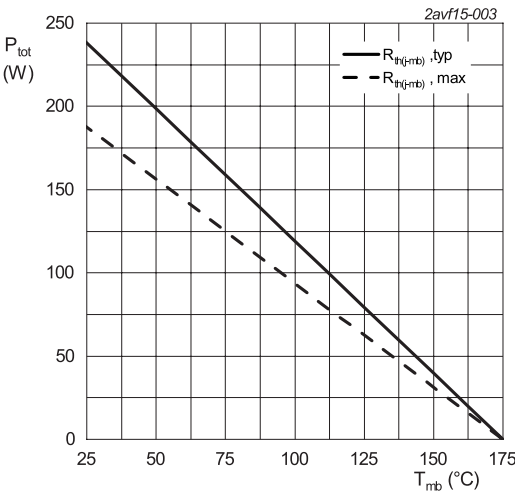


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	0.63	0.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W

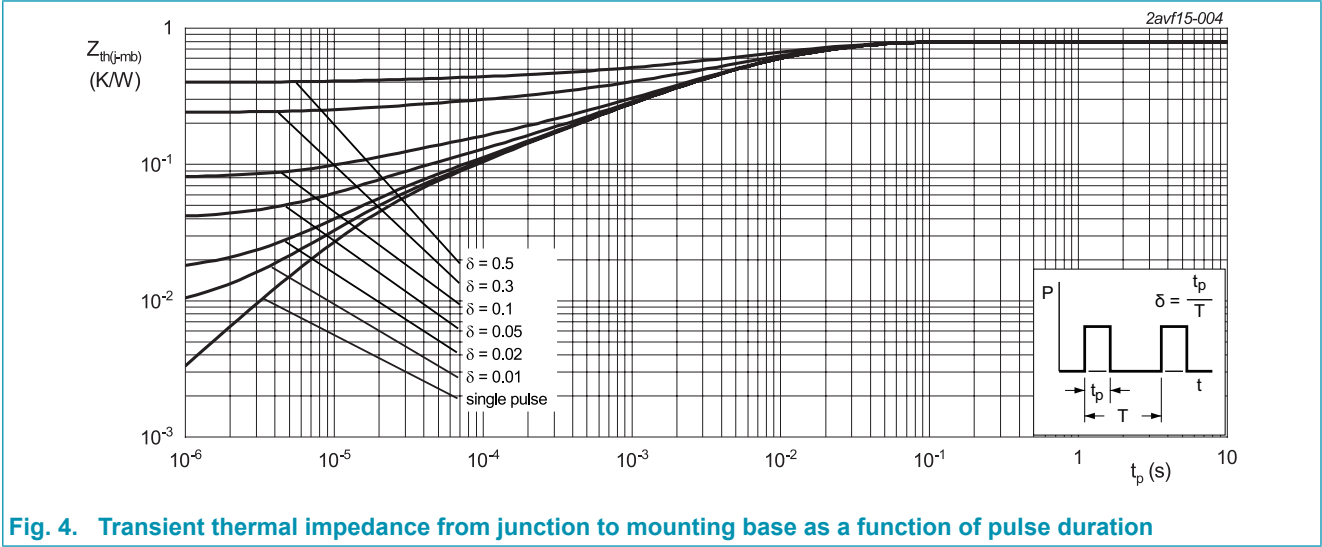
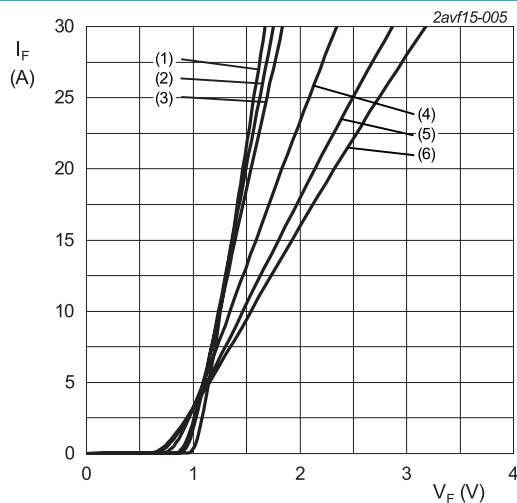


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 20 A; T _j = 25 °C; Fig. 5		-	1.54	1.75	V
		I _F = 20 A; T _j = 150 °C; Fig. 5		-	2.15	2.60	V
		I _F = 20 A; T _j = 175 °C; Fig. 5		-	2.35	2.80	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C; Fig. 6		-	1	75	μA
		V _R = 1200 V; T _j = 175 °C; Fig. 6		-	25	-	μA
Dynamic characteristics							
Q _r	recovered charge	I _F = 20 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _j = 25 °C; Fig. 7		-	36	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C		-	800	-	pF
		f = 1 MHz; V _R = 400 V; T _j = 25 °C		-	66	-	pF
		f = 1 MHz; V _R = 800 V; T _j = 25 °C		-	48	-	pF
E _{as}	non-repetitive avalanche energy	I _R = 4.7 A; L = 10 mH; T _{j(init)} = 25 °C		110	-	-	mJ



$V_o = 1.268\text{ V}$; $R_s = 0.0662\text{ }\Omega$

- (1) $T_J = -55\text{ }^\circ\text{C}$; typical values
- (2) $T_J = 0\text{ }^\circ\text{C}$; typical values
- (3) $T_J = 25\text{ }^\circ\text{C}$; typical values
- (4) $T_J = 100\text{ }^\circ\text{C}$; typical values
- (5) $T_J = 150\text{ }^\circ\text{C}$; typical values
- (6) $T_J = 175\text{ }^\circ\text{C}$; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

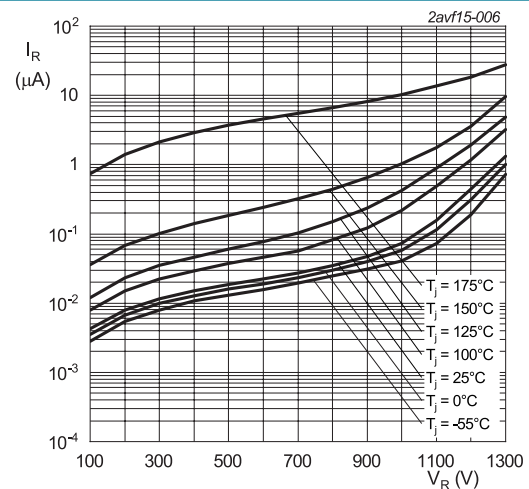


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

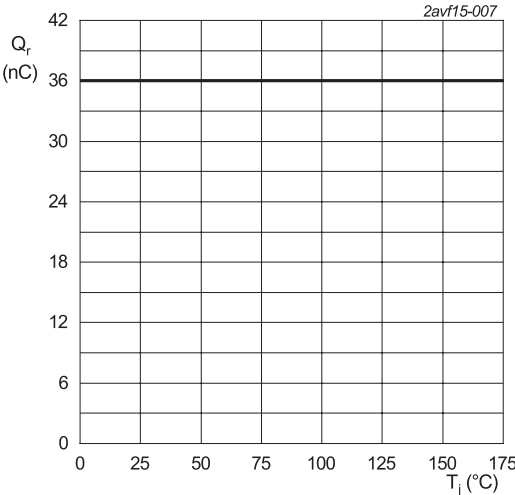
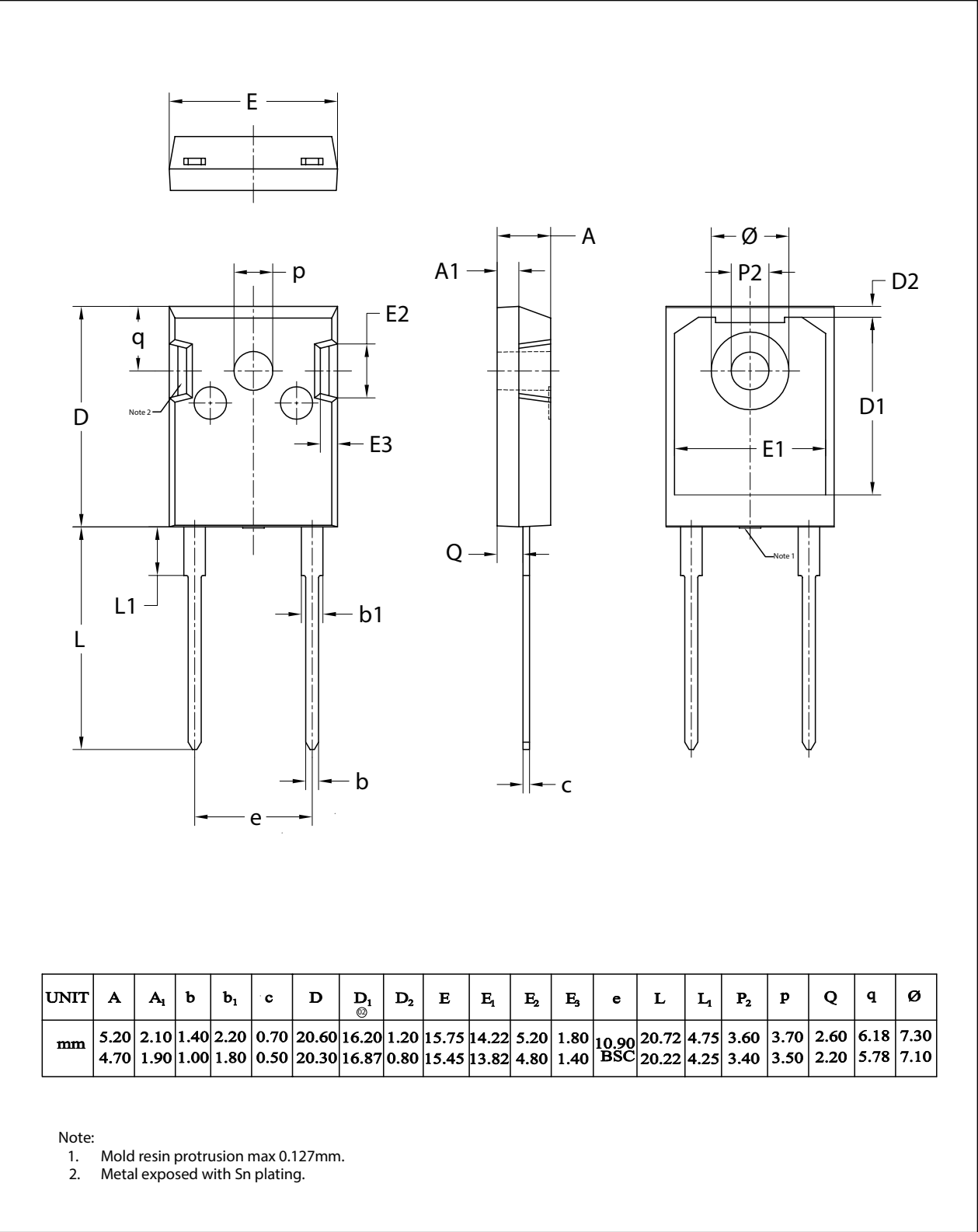


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended through-hole package; heatsink mounted;1 mounting hole; 2 leads TO-247

TO247-2L



UNIT	A	A ₁	b	b ₁	c	D	D ₁	D ₂	E	E ₁	E ₂	E ₃	e	L	L ₁	P ₂	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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